

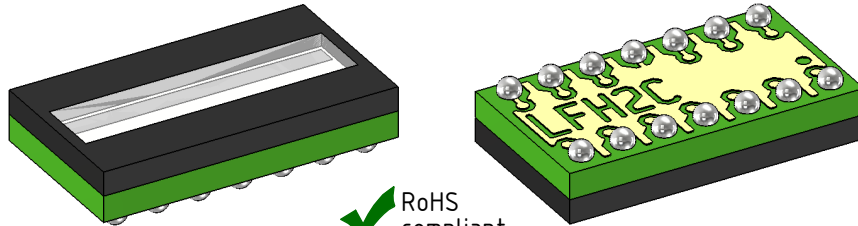
iC-LFH640 oBGA LFH2C

PACKAGE SPECIFICATION



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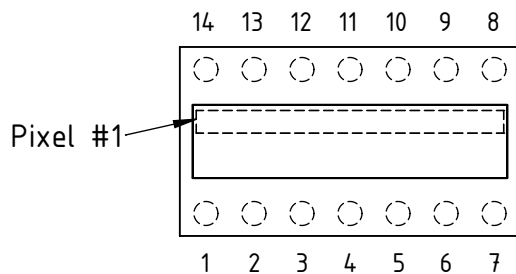
PACKAGE VIEW



SIZE 9.0 mm x 5.0 mm

PIN CONFIGURATION

(top view)



PIN FUNCTIONS

No.	Name	Function
1	RES0	Select Resolution Bit 0
2	RES1	Select Resolution Bit 1
3	VDD	Digital Supply +5V
4	GND	Digital Ground
5	ETP	Enable Test Mode*
6	SI	Start of Integration
7	CLK	Clock
8	BNA	Select Binning/Averaging
9	ESH	Enable Shutter
10	NRES	Power-Down Reset Output (low active)
11	GNDA	Analog Ground
12	VDDA	Analog Supply +5V
13	VAO	Pixel Output Supply Voltage
14	AO	Analog Pixel Output

*ETP must be connected to GND/GNDA

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Parameter	Conditions	Value		
				Min	Max	Unit
G001	Ta	Operating Ambient Temperature Range	Consider self heating to stay below max. junction temperature (Tj) of iC-LFH640	-25	85	°C
G002	Ts	Storage Temperature Range		-25	110	°C
G003	Tpk	Reflow Soldering Peak Temperature	tpk < 20 s, convection reflow tpk < 20 s, vapour phase Floor life: 8h; TOL (time on label) See CUSTOMER INFORMATION #7 for details		245 230	°C °C

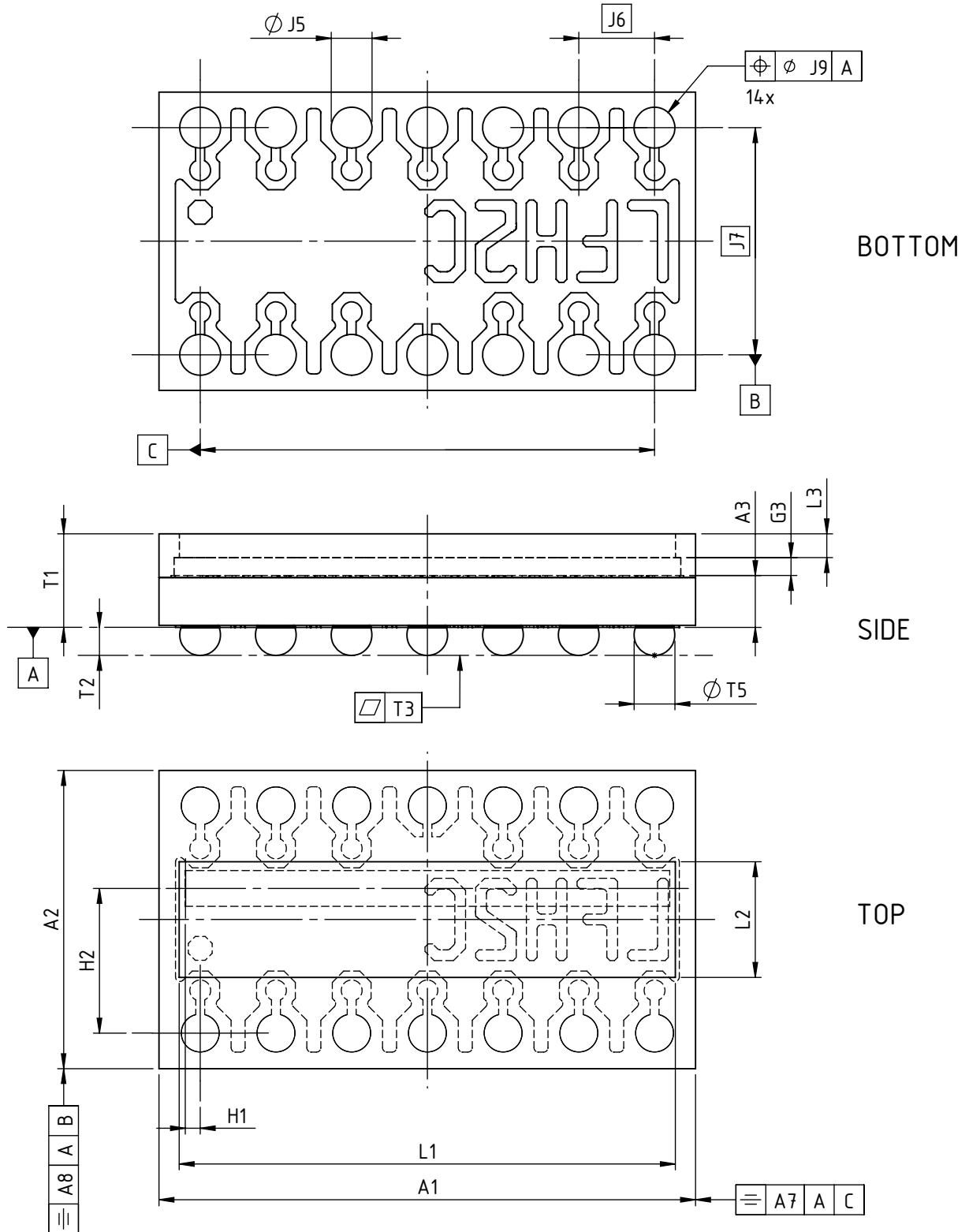
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PACKAGE SPECIFICATION



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PHYSICAL DIMENSIONS



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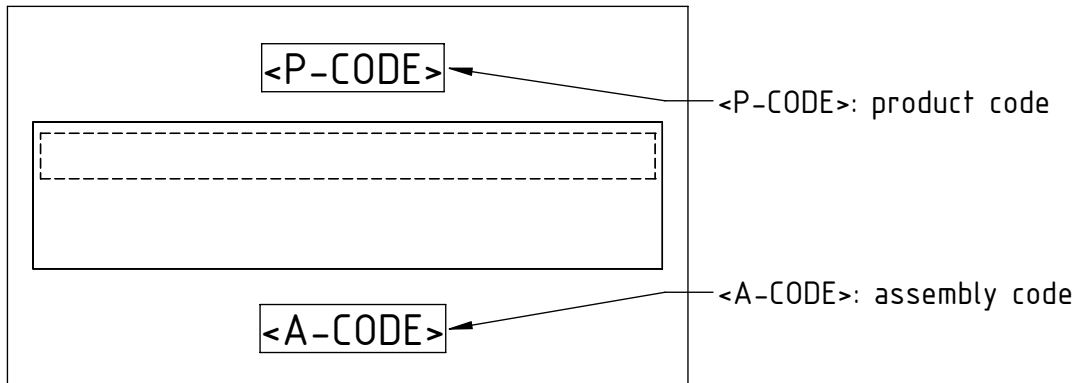
DIMENSION TABLE

Item	Parameter	Comment					Unit
			Min.	Typ.	Max.	Tol.	
Substrate							
A1	Outline X			9.00		±0.10	mm
A2	Outline Y			5.00		±0.10	mm
A3	Substrate Thickness	bottom substrate to bottom die typical value		0.90			mm
A7	Outline Symmetry X	vs. bottom metal pattern			0.20		mm
A8	Outline Symmetry Y	vs. bottom metal pattern			0.20		mm
Chip							
G3	Chip Thickness			0.30			mm
Chip Placement							
H1	Pixel Array Position vs. Bottom Metal Pattern X	bottom metal pattern vs. center of 1 st pixel		0.24765		±0.175	mm
H2	Pixel Array Position vs. Bottom Metal Pattern Y	bottom metal pattern vs. center of 1 st pixel		2.425		±0.175	mm
Bottom Metal Pattern							
J5	Lead Diameter			0.635		±0.03	mm
J6	Lead Pitch X (or Lead to Lead Distance X)			1.27			mm
J7	Lead Pitch Y (or Lead to Lead Distance Y)			3.81			mm
J9	Lead to Lead Position Tolerance				0.10		mm
Glass Cover							
L1	Glass Size X			8.40			mm
L2	Glass Size Y			1.94			mm
L3	Glass Thickness			0.40			mm
Encapsulation							
E1	Coating Excess	surface glass to surface coating			0.05		mm
Thickness Specification							
T1	Overall Thickness	bottom substrate to top of glass (nominal glass thickness of 0.4mm) ¹⁾	1.40	1.60	1.80		mm
T2	Solder Ball Height	drawing not to scale	0.40		0.54		mm
T3	Solder Ball Planarity				0.10		mm
T5	Solder Ball Diameter			0.635			mm

Notes:

1) Coating normally adjusted to top surface of glass.

MARKING



dra_lfh2c-lfh640_0_pack_4, 10:1

Appearance of Laser marking varies by tool.

GENERAL HANDLING INSTRUCTIONS

See [CUSTOMER INFORMATION #7](#) for details.

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REVISION HISTORY

Rel.	Rel. Date*	Chapter	Modification	Page
A1	2015-07-27		Initial	

Rel.	Rel. Date*	Chapter	Modification	Page
A2	2016-10-07		Update drawing PIN CONFIGURATION; update DIMENSION TABLE items H1, H2	1, 3

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* Release Date format: YYYY-MM-DD

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ORDERING INFORMATION

Type	Package	Options	Order Designation
iC-LFH640	optoBGA™ LFH2C	none	iC-LFH640 oBGA LFH2C

Please send your purchase orders to our order handling team:

Fax: +49 (0) 61 35 - 92 92 - 692
E-Mail: dispo@ichaus.com

For technical support, information about prices and terms of delivery please contact:

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